

ABSTRACT

A dicing/die bonding integrated film of the present disclosure includes a base layer, a pressure-sensitive adhesive layer having a first surface facing the base layer and a second surface opposite to the first surface, and an adhesive layer provided to cover a center portion of the second surface. The pressure-sensitive adhesive layer has a first region including at least a region corresponding to a pasting position of a wafer in the adhesive layer, and a second region located to surround the first region. The first region is a region in a state where adhesive force is lowered by irradiation of active energy rays as compared to the second region, and the adhesive force of the first region with respect to the adhesive layer as measured at a temperature of 23°C under conditions of a peeling angle of 30° and a peeling rate of 60 mm/min is 1.2 N/25 mm or more and 4.5 N/25 mm or less.

Fig. 1